

42390.P955



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#8 *Amend*  
*P. B. L.*  
*9/4/01*  
RECEIVED  
SEP 11 2001  
TC-2880 MAIL ROOM

In re Application of:

Mu, et al.

Serial No.: 09/661,899

Filed: September 14, 2000

For: PROCESS FOR FORMING A  
DIRECT BUILD-UP LAYER ON AN  
ENCAPSULATED DIE PACKAGE  
AND INTERMEDIATE  
STRUCTURES FORMED  
THEREWITH

Examiner: A. Chambliss

Group Art Unit: 2814

Attorney Docket No.: 42390.P8497

CERTIFICATE OF MAILING

I hereby certify that this paper or fee along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail (under 37 C.F.R. § 1.8(a)) on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner of Patents and Trademarks, Washington, D.C. 20231.

9/4/01  
Date of Deposit

*Deborah O. H. Q.*  
Signature of registered practitioner or other person  
having reasonable basis to expect mailing to occur  
on date of deposit shown pursuant to 37 C.F.R. §  
1.8(a)(1)(ii)

DEBORAH L. HIGHAM  
Typed/printed name of person whose signature is  
contained above

RESPONSE TO RESTRICTION REQUIREMENT  
AND PRELIMINARY AMENDMENT

Hon. Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

In response to the Restriction Requirement mailed August 3, 2001 and prior to the examination of the claims on the merits, Applicants respectfully request that the Examiner enter the following amendments:

*A*